

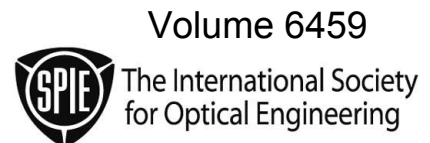
PROCEEDINGS OF SPIE

Laser-based Micro- and Nanopackaging and Assembly

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22–24 January 2007
San Jose, California, USA

Sponsored and Published by
SPIE—The International Society for Optical Engineering



Proceedings of SPIE—The International Society for Optical Engineering, 9780819465726, v. 6459

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Author(s), "Title of Paper," in *Laser-based Micro- and Nanopackaging and Assembly*, edited by Wilhelm Pfleging, Yongfeng Lu, Kunihiko Washio, Friedrich G. Bachmann, Willem Hoving, Proceedings of SPIE Vol. 6459 (SPIE, Bellingham, WA, 2007) Article CID Number.

ISSN 0277-786X
ISBN 9780819465726

Published by
SPIE—The International Society for Optical Engineering
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone 1 360/676-3290 (Pacific Time) · Fax 1 360/647-1445
<http://www.spie.org>

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Printed in the United States of America.

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